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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/659,337	09/11/2003	Hitoshi Haematsu	020721A	7094
23850	7590 03/23/2005		EXAMINER	
ARMSTRONG, KRATZ, QUINTOS, HANSON & BROOKS, LLP			PERKINS, PAMELA E	
1725 K STR SUITE 1000	•	•	ART UNIT	PAPER NUMBER
WASHING	ON, DC 20006		2822	
			DATE MAILED: 03/23/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)	
Office Action Comme		10/659,337	HAEMATSU, HITOSHI	
	Office Action Summary	Examiner	Art Unit	
		Pamela E. Perkins	2822	
Period f	The MAILING DATE of this communication apports Reply	ears on the cover sheet with the c	orrespondence address	
THE - Extending - If the - If NO - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. Insigns of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. In period for reply specified above is less than thirty (30) days, a reply of period for reply is specified above, the maximum statutory period we are to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be ting within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).	
Status		•		
1)[Responsive to communication(s) filed on 23 De	ecember 2004.		
2a) <u></u> ☐	This action is FINAL. 2b)⊠ This	action is non-final.		
3)□	Since this application is in condition for alloward closed in accordance with the practice under E	•		
Disposit	ion of Claims		•	
5)□ 6)⊠ 7)□	Claim(s) 1-3 is/are pending in the application. 4a) Of the above claim(s) is/are withdray Claim(s) is/are allowed. Claim(s) 1-3 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or			
Applicat	ion Papers		•	
9)[The specification is objected to by the Examine	г.		
10)	The drawing(s) filed on is/are: a) acce	epted or b) objected to by the l	Examiner.	
	Applicant may not request that any objection to the	drawing(s) be held in abeyance. See	∋ 37 CFR 1.85(a).	
11)□	Replacement drawing sheet(s) including the correction The oath or declaration is objected to by the Ex		•	
Priority (ınder 35 U.S.C. § 119			
а)	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority application from the International Bureau See the attached detailed Office action for a list of	s have been received. s have been received in Application ity documents have been received (PCT Rule 17.2(a)).	on No ed in this National Stage	
Attachmen		·	(DTO 440)	
2) 🔲 Notic 3) 🔯 Infori	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date 12/28/04.	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	•	
•			•	

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DETAILED ACTION

This office action is in response to the filing of the request for reconsideration on 23 December 2004. Claims 1-3 are pending.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-3 are rejected under 35 U.S.C. 103(a) as being unpatentable over Harumi (JP 61019154) in view of Hajime (JP 08107120).

Harumi discloses a manufacturing method of a semiconductor device where an electrode is formed on a front face of a semiconductor chip (4); covering the front face the semiconductor chip (4), with a resin insulating film (1); and covering all of an upper surface and side surfaces the resin insulating film (1) with a metal protective film (9) (constitution). Harumi does not disclose forming a plurality of electrodes and providing an electrical connecting portion of at least any of the plurality of electrodes at a reverse face of the semiconductor chip and exposing one of the plurality of electrodes from the upper surface be connected to the metal protective film.

Hajime discloses a manufacturing method of a semiconductor device where a plurality of electrodes (11, 12, 13) are formed on front face of a semiconductor chip; covering the front face of the semiconductor chip with a metal protective film (15),

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wherein a space (19) is left between the front face of the semiconductor chip and the metal protective film (15); and providing an electrical connecting portion of at least any of the plurality of electrodes (13) at a reverse face of the semiconductor chip (para. 22).

Since Harumi and Hajime are both from the same field of endeavor, a manufacturing method of a semiconductor device, the purpose disclosed by Hajime would have been recognized in the pertinent art of Harumi. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Harumi by forming a plurality of electrodes and providing an electrical connecting portion of at least any of the plurality of electrodes at a reverse face of the semiconductor chip as taught by Hajime to operate the circuit with stability and reduce production cost (para. 4).

Referring to claim 2, Harumi discloses forming a metal layer (2) on a peripheral isolation region on front face the semiconductor chip when covering the side surface of peripheral the resin insulating film (1) with the metal film (9) (constitution).

Referring to claim 3, Hajime discloses exposing one of the plurality of electrodes (12) from the upper surface be connected to the metal protective film (15) (para. 23).

Response to Arguments

Applicant's arguments with respect to claims 1-3 have been considered but are most in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Pamela E. Perkins whose telephone number is (571) 272-1840. The examiner can normally be reached on Monday thru Friday, 9:00am to 5:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

PEP

AMIR ZARABIAN

CONTRACTORY PATENT EXAMINER

CONTRACTORY CENTER 28-13